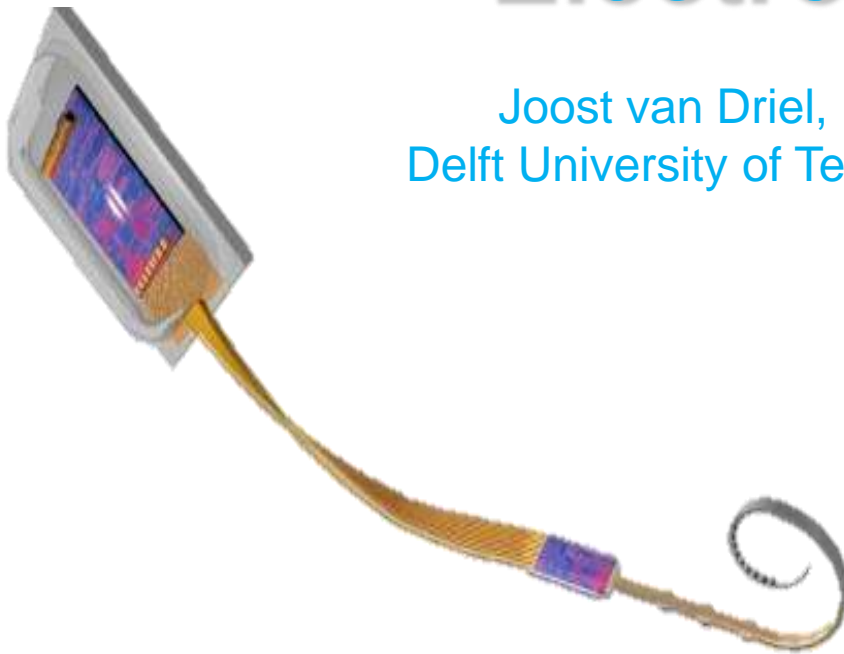


Electric Field Density Distribution for Cochlear Implant Electrodes

Joost van Driel, BSc.
Delft University of Technology



1

Contents

- Cochlear Implant history, basics & problems
- Silicon electrode design
- Comsol 4.2 a ® Simulations
- Simulation results
- Conclusion and Future Work

History



1855 - Ear trumpet

1930 – Vacuum tube



1953 – Transistor



1994 – In-Ear



1984 – Cochlear Implant



Cochlear Implant (CI) & problems

External part

Internal part

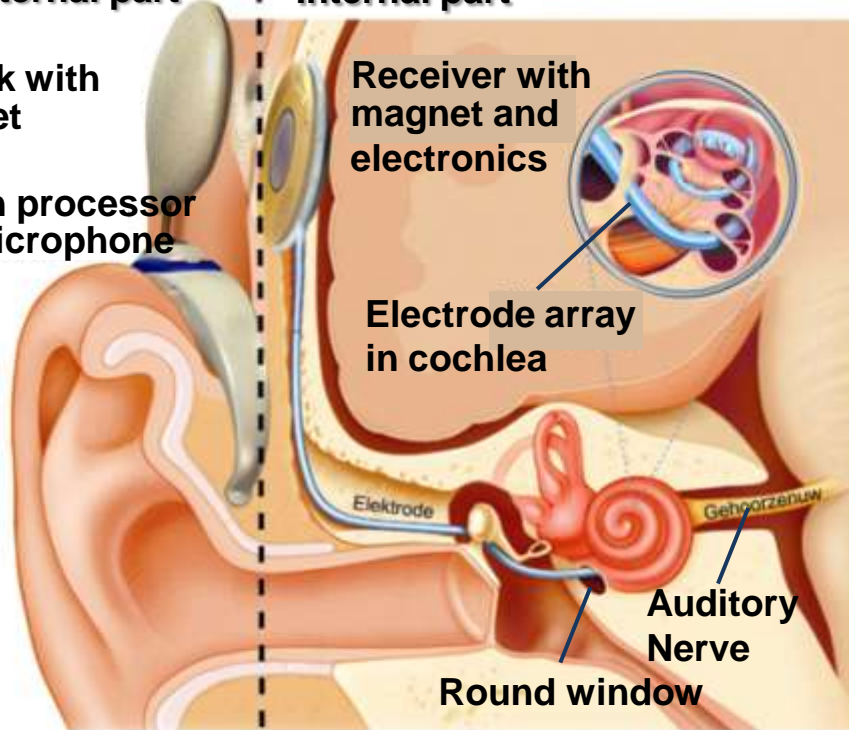
RF-link with magnet

Speech processor with microphone

Receiver with magnet and electronics

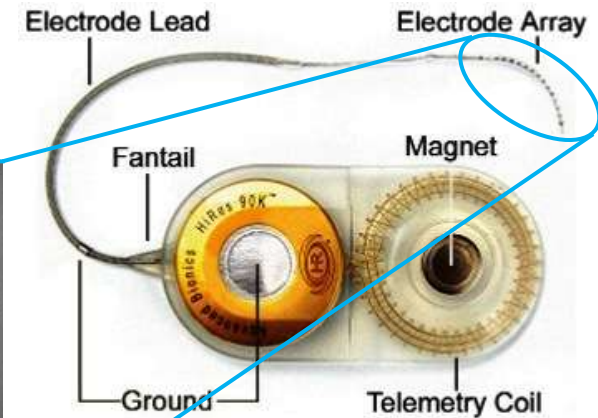
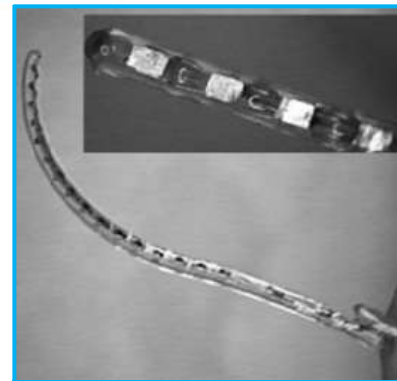
Electrode array in cochlea

Auditory Nerve
Round window



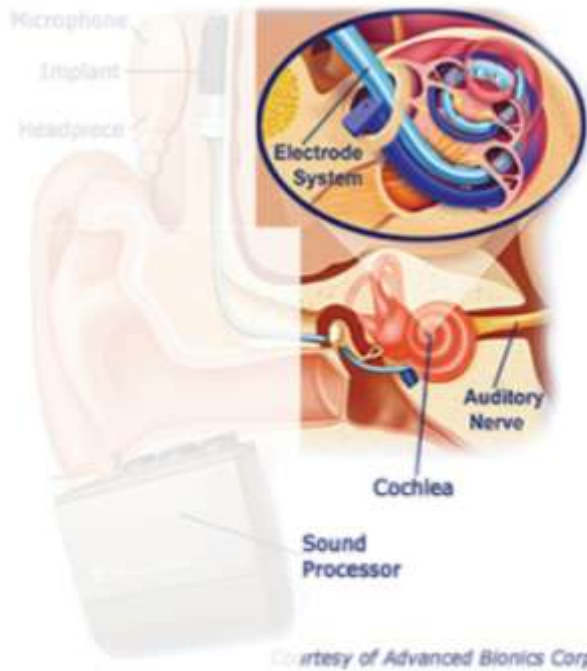
- To reduce size and power consumption
- To prevent electrode breakage and tissue damage during insertion.
- Cocktail party effect.
- Delivery of more sound details to the current electrodes.
- Appreciate music.
- To reduce surgery & manufacturing cost

Details of CI with a closer view of the electrode array

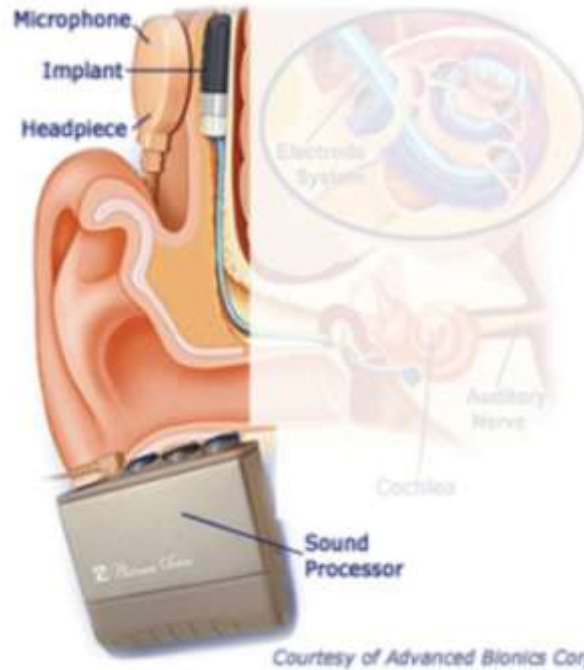


Framework of Smac-it project

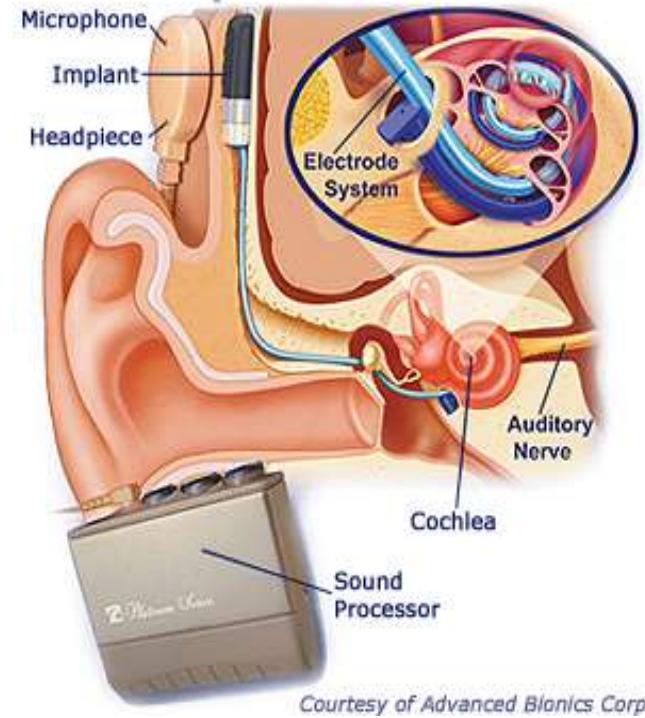
Electrode design and fabrication



Low power electronics and low level integration



Complete System level Optimizations



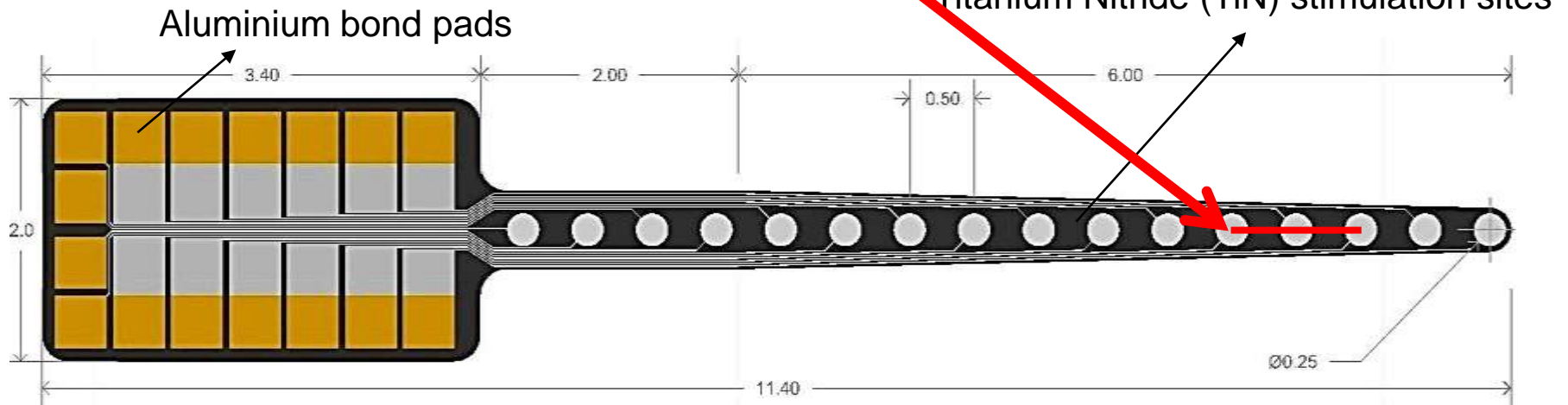
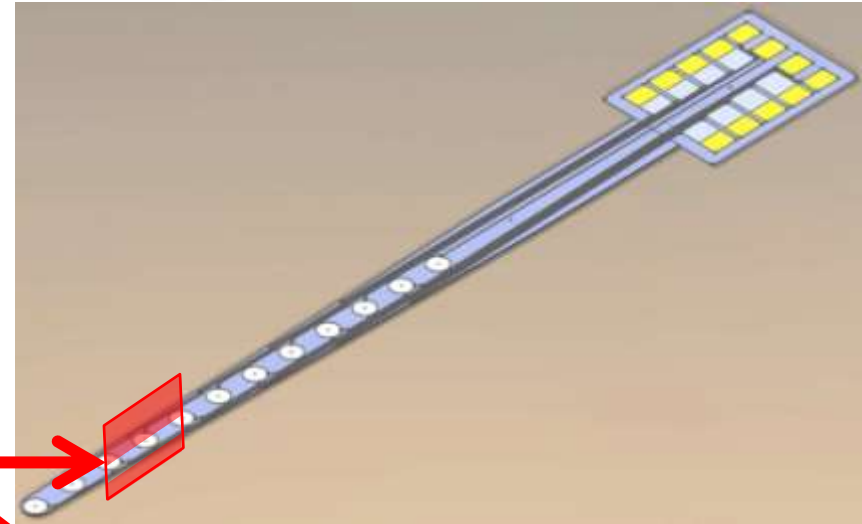
Nishant Lawand
Joost van Driel
Supervisors : Prof. Dr. P J. French
Prof. Dr. ir. J H M. Frijns

Wannaya Ngamkham
Supervisor : Dr. ir. W A. Serdijn

Ghazaleh Nazarian
Supervisor: Dr. G N.
Gaydadjiev

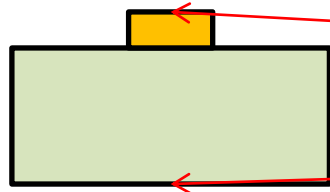
Electrode design

- TiN stimulation sites: 16
- Diameter of TiN site: $72\ \mu\text{m}$
- Distance between 2 sites: $150\ \mu\text{m}$
- Aimed thickness of TiN site: $200\ \text{nm}$
- Cross-section



Simulations (1)

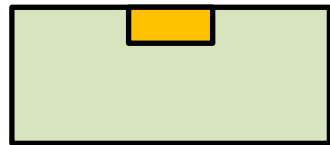
- Electric Field Distribution Evaluation
- Cross Section (2D)
- Protruded Design



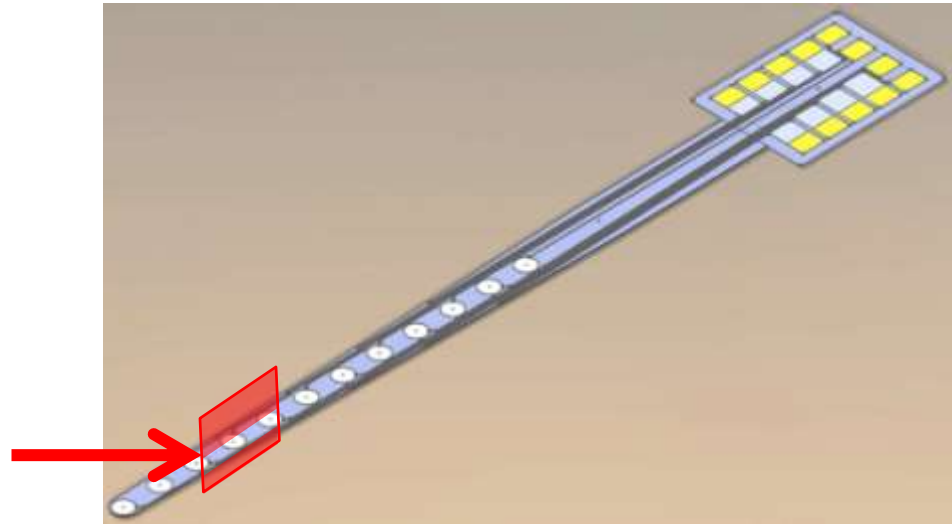
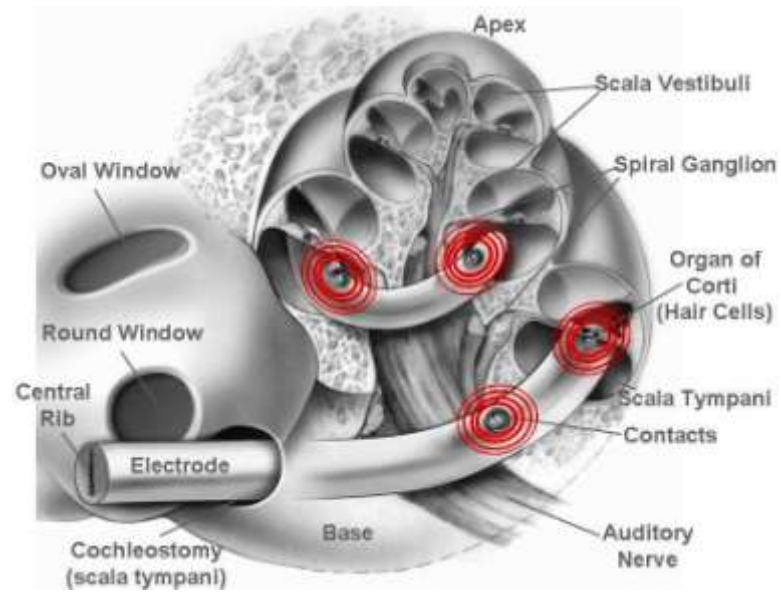
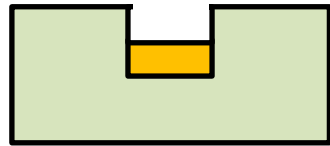
Titanium Nitride
(200 nm thick)

Silicon Substrate
(20 μm thick)

- Planar Design

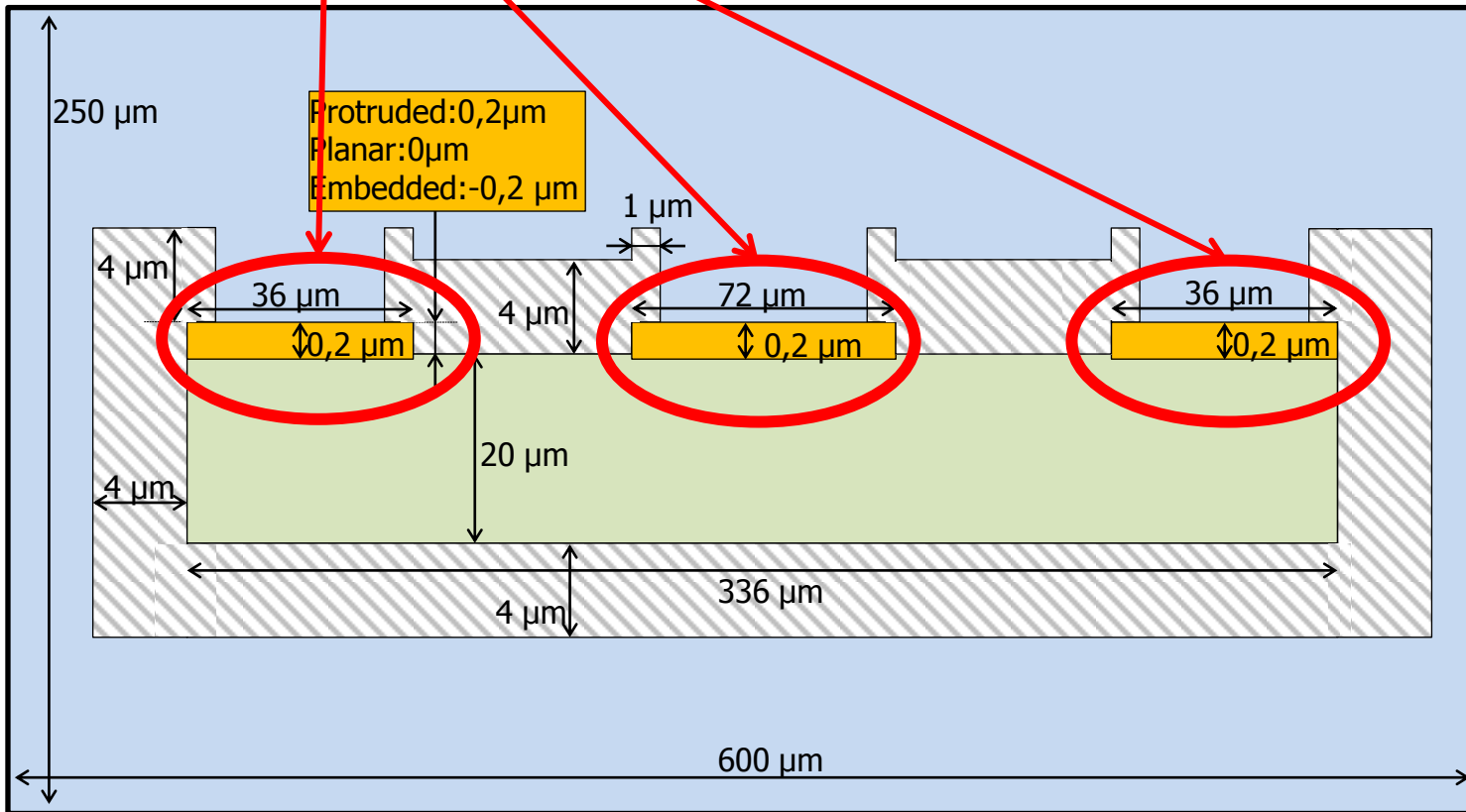
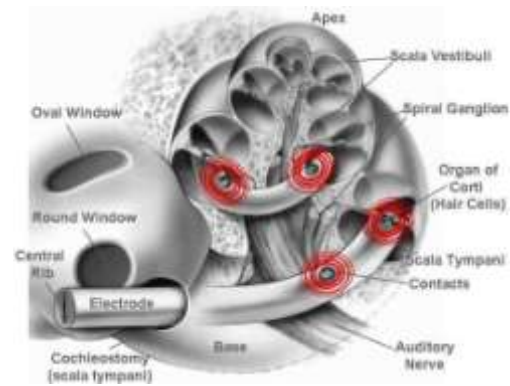


- Embedded Design



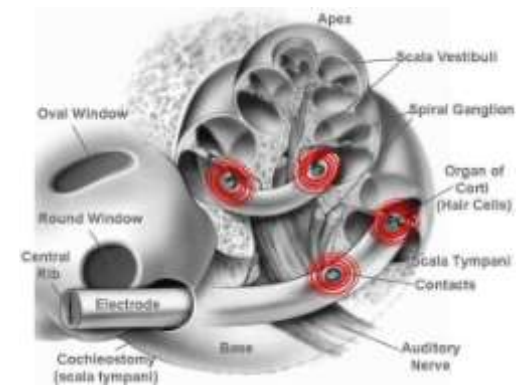
Simulations (2)

Titanium Nitride Electrodes
Silicon Substrate
Parylene
Perilymph (Fluid in Cochlea)



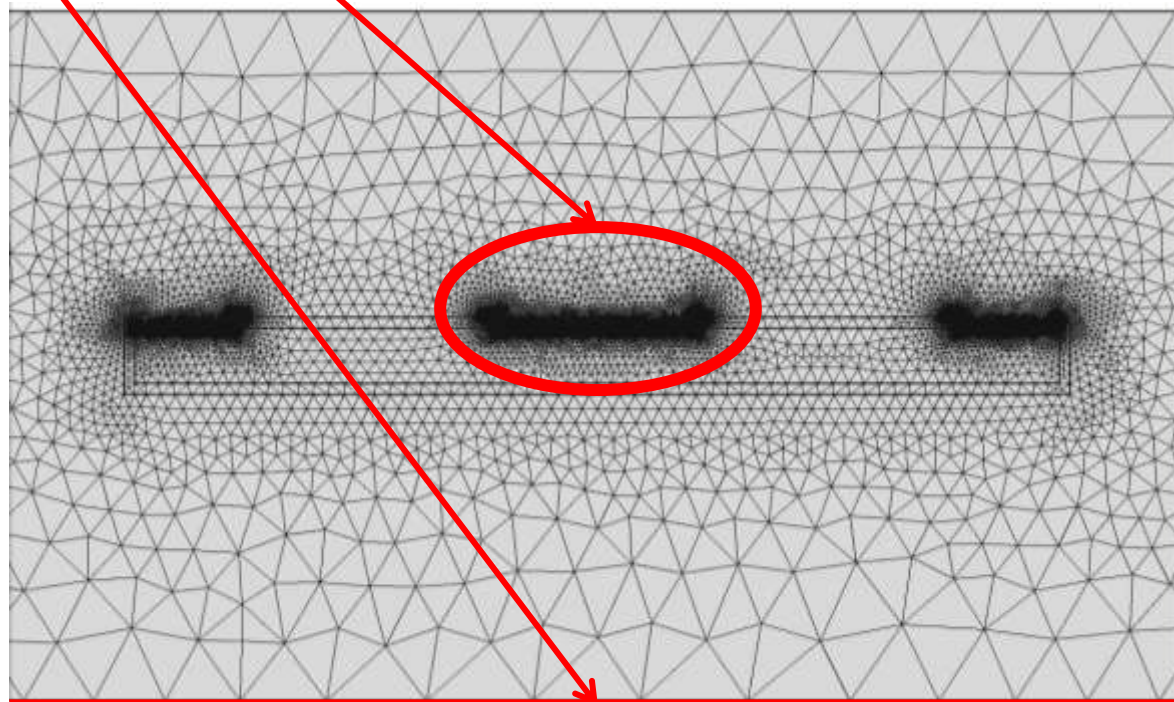
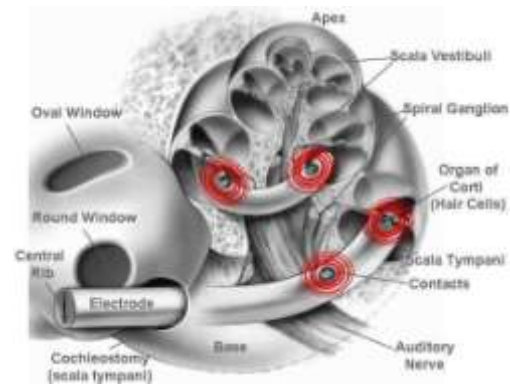
Simulations (3)

Name	Electrical Conductivity, sigma (S/m)	Relative Permittivity, ϵ_r
Titanium Nitride	5000	100
Silicon	4.3e-4	11.7
Perilymph	2	50
Parylene HT	5e-20	2.2



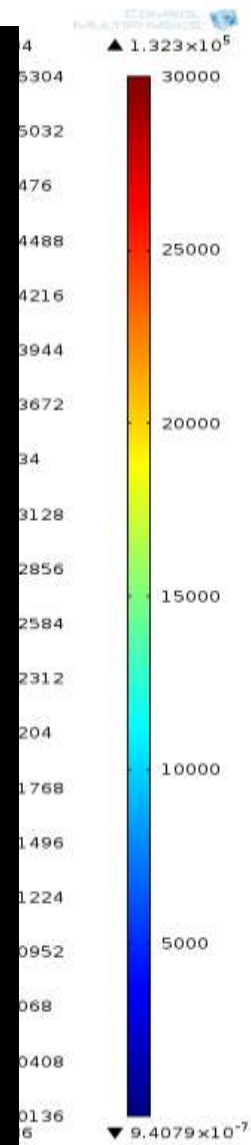
Simulations (4)

- Comsol 4.2 - AC/DC Module
 - *Electric Currents*
- 544 mV on centre electrode
- Bottom boundary of Perilymph: Ground
- Parametric Sweep for different designs



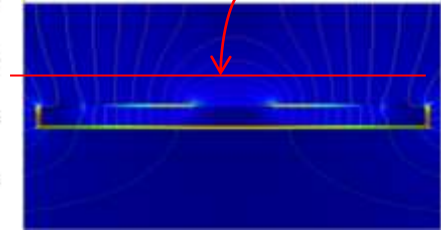
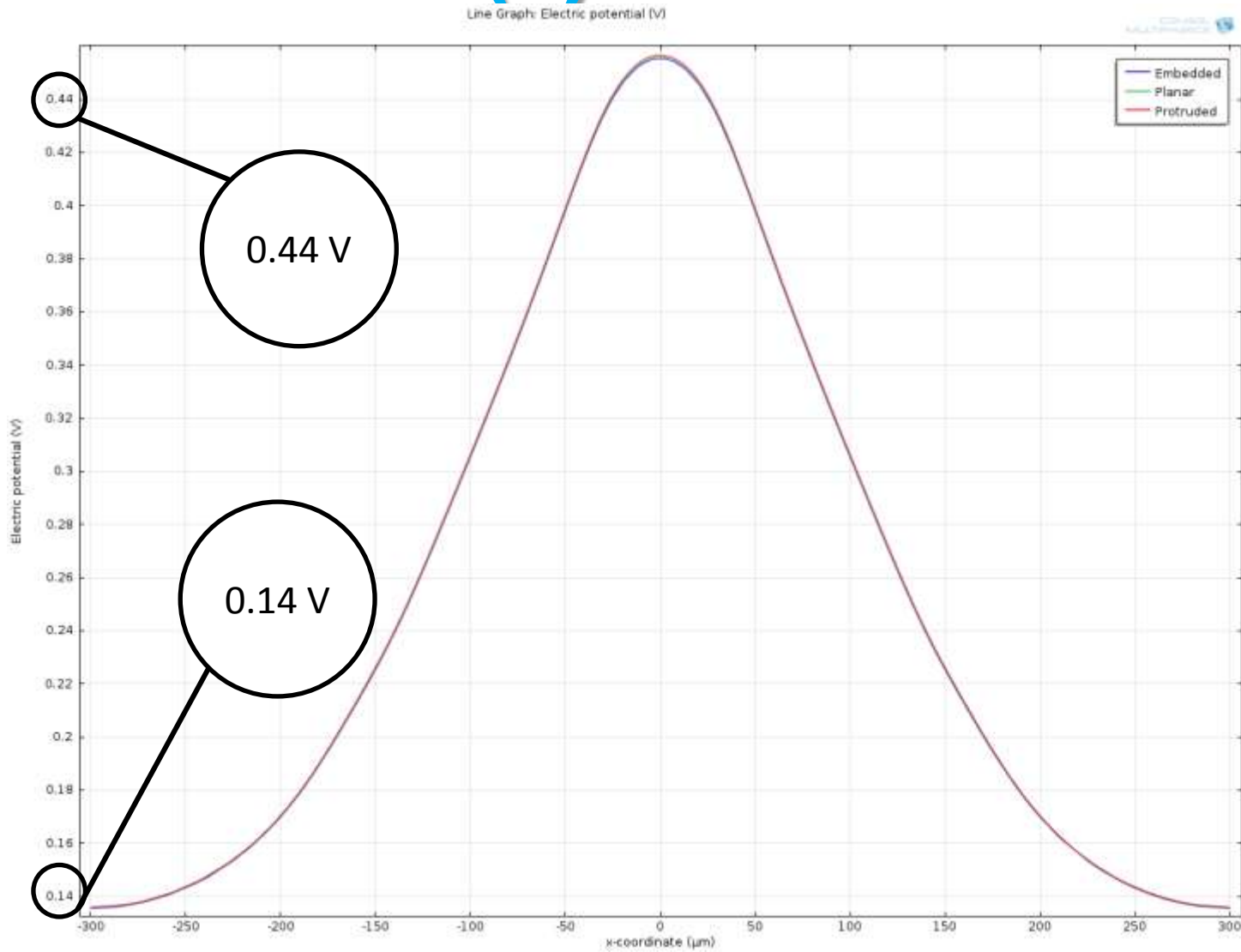
Results (1)

ht(3) = 0.2 Surface: Electric field norm (V/m) Contour: Electric potential (V)



Results (2)

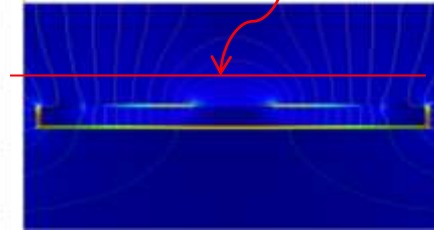
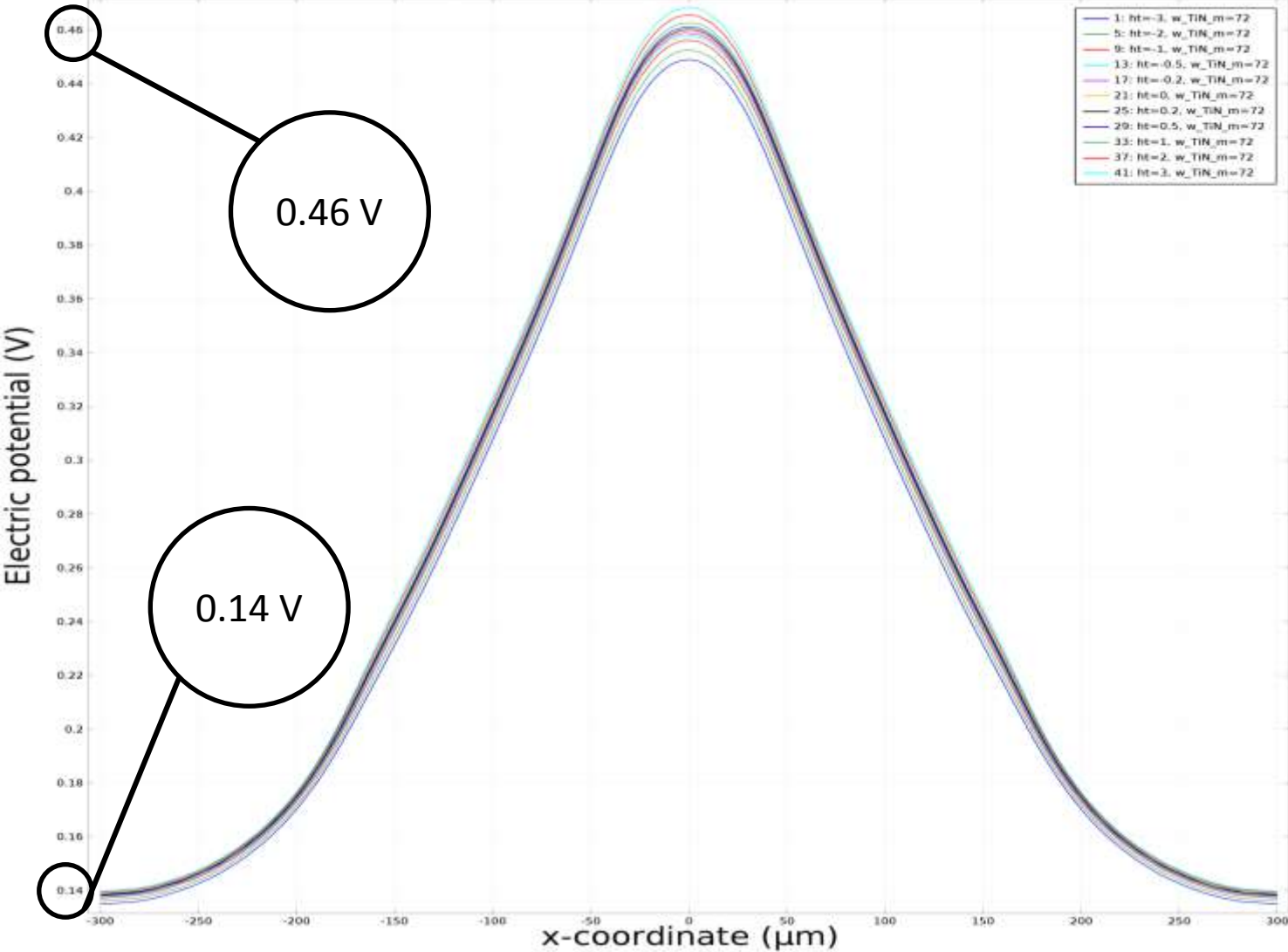
Potential at 30 μm from surface



Results (3um offset)

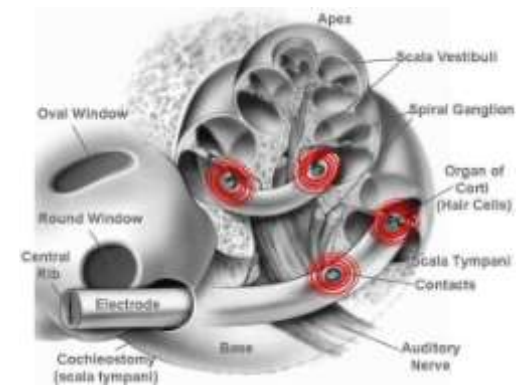
Line Graph: Electric potential (V)

Potential at 30 μm from surface



Conclusions

- Negligible difference between 3 designs
- Choice depends on fabrication
 - *Protruded*



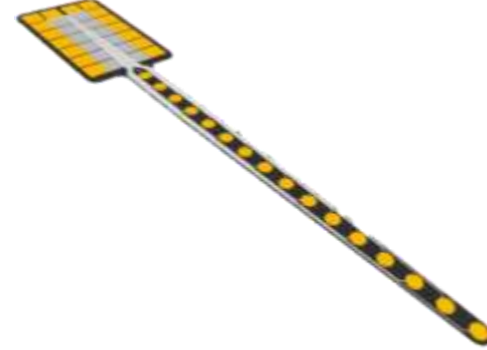
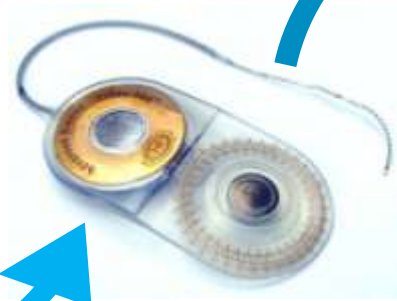
Future Work

- Characterization of materials
 - *Biocompatibility*
 - *Maximum Current Density*
- Creating flexible devices
- Increasing the amount of electrodes
- Embedding electronics
- Insertion techniques

Thank you.



Electrode array Development.

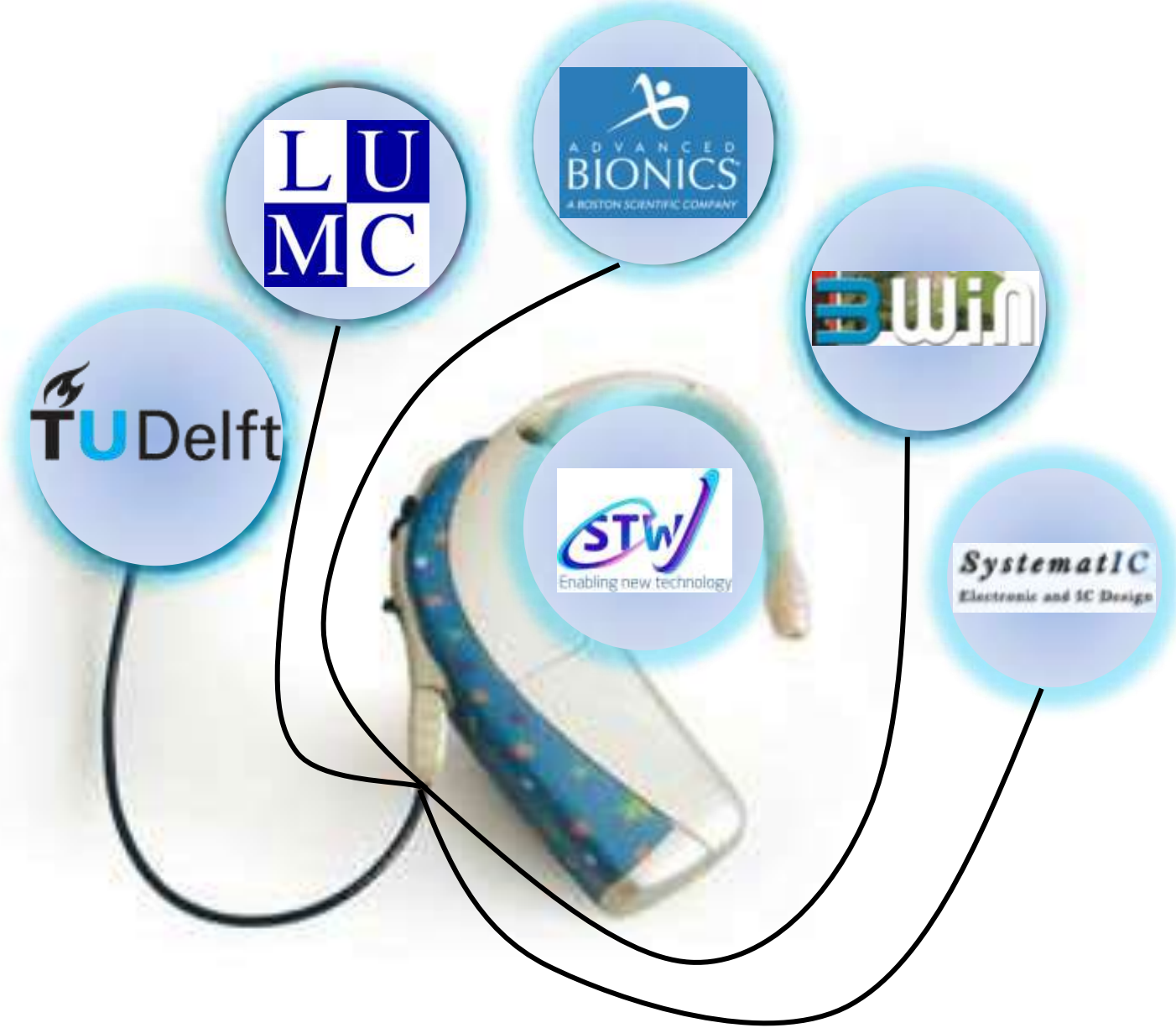


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Delft University of Technology

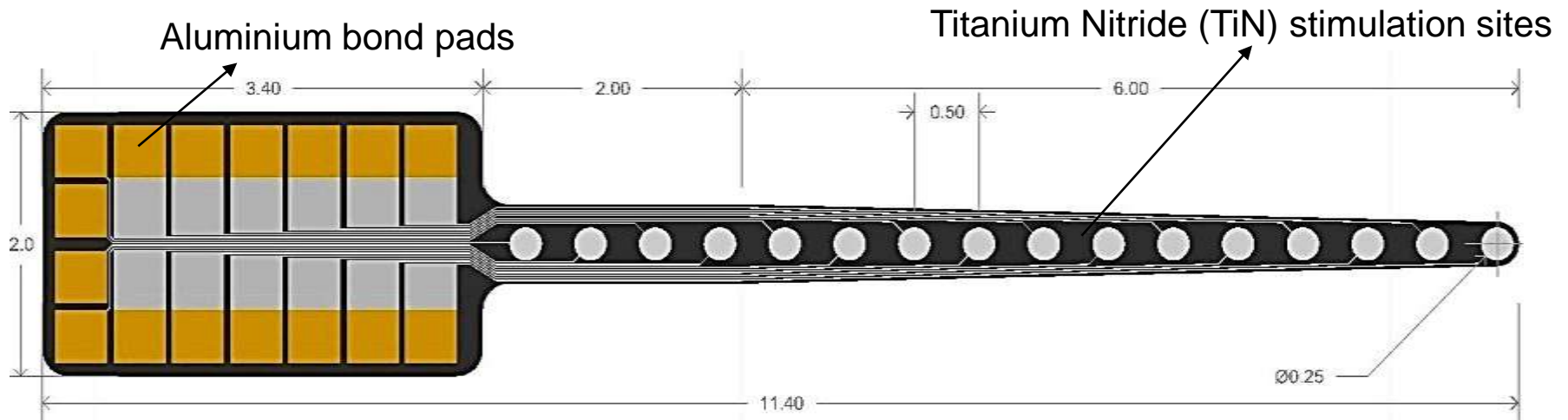
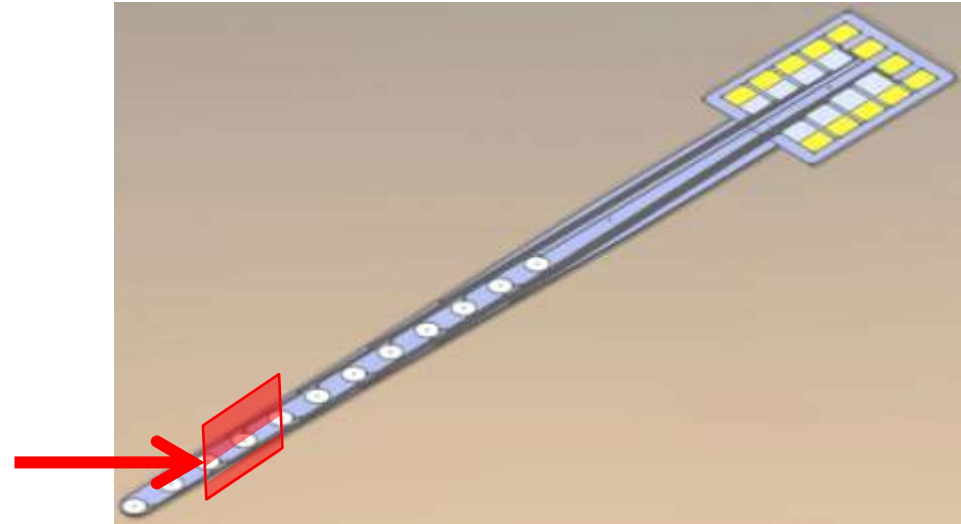
2: Department of ORL-HNS,
Leiden University Medical Center



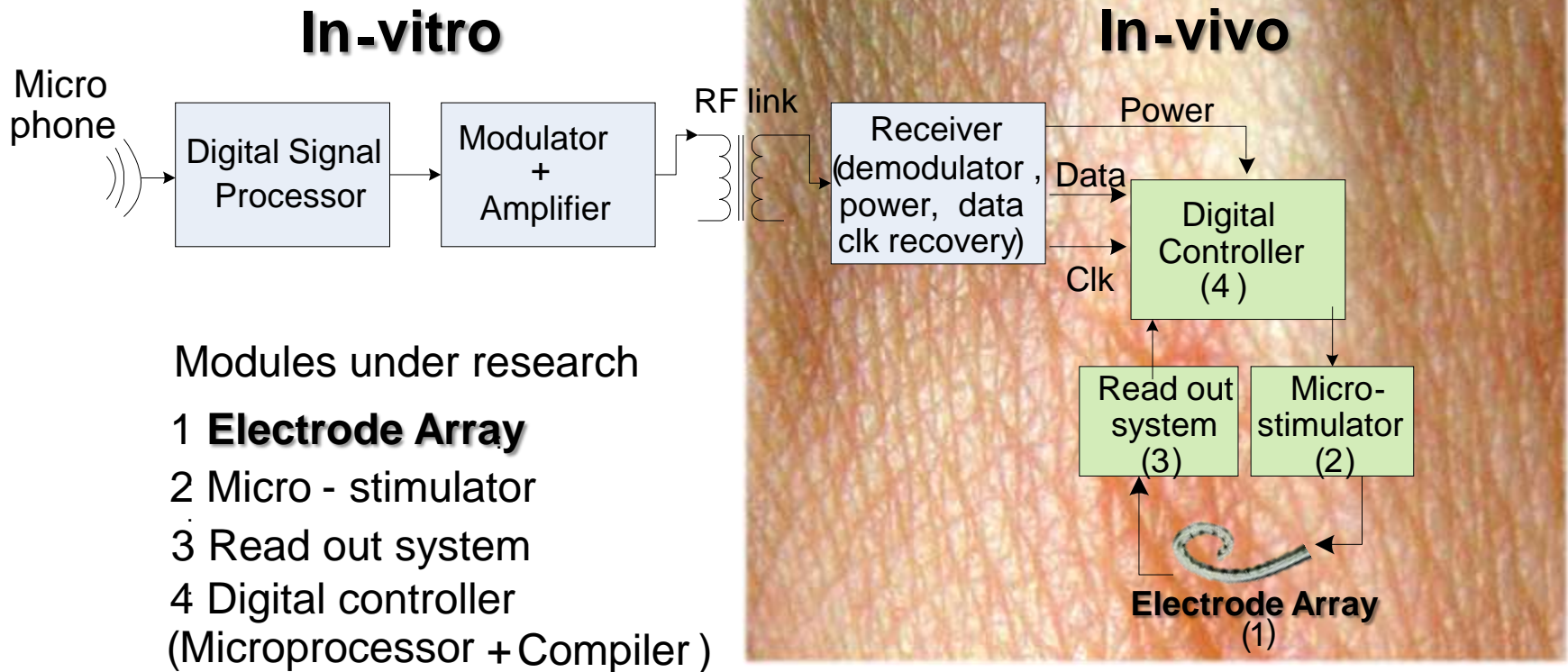


Electrode design

- TiN stimulation sites: 16
- Diameter of TiN site: $72\ \mu\text{m}$
- Distance between 2 sites: $150\ \mu\text{m}$
- Aimed thickness of TiN site: $200\ \text{nm}$
- Width of metal line: $4\ \mu\text{m}$
- Distance between 2 metal lines: $5\ \mu\text{m}$
- Bond pad size: $130 \times 130\ \mu\text{m}$



Block diagram of a modern cochlear implant (CI)



Publications



- N. S. Lawand, P. J. French, J. J. Briaire, J. H. M. Frijns: Study of fabrication strategies for Silicon in Cochlear Implants, Proc. SAFE 2009, pp. 28-31, November, 2009.
- N. S. Lawand, P. J. French, J. J. Briaire, J. H. M. Frijns: Silicon Probes for Cochlear Auditory Nerve Stimulation and Measurement, Proc. International Conference on Materials for Advanced Technologies (ICMAT 2011), Advanced Materials Research Vol. 254, pp. 82-85, June-July 2011.
- N. S. Lawand, P. J. French, J. J. Briaire, J. H. M. Frijns: “Development of probes for cochlear implants”, IEEE Sensors, pp. 1827-1830, 2011.
- N. S. Lawand, P. J. French, J. J. Briaire, J. H. M. Frijns: Design and fabrication of silicon stiff probes: A step towards developed cochlear implant electrodes, Proc. Euroensors XXV, Sept. 2011. (Invitation for extended special issue journal paper for Sensor & Actuators Invitation devoted to EUROSENSORS 2011 - Athens, Greece).
- N. S. Lawand, P. J. French, J. J. Briaire, J. H. M. Frijns: “Development of microelectrode material for nerve stimulation using TiN”, Proc. International conference on Materials and Applications for Sensors and Transducers, Budapest, Hungary, May 24-28, 2012 (Best presentation award).
- N. S. Lawand, P. J. French, J. J. Briaire, J. H. M. Frijns: “Cochlear Implant electrode improvement for long term implants”, 34th Annual International conference of the IEEE EMBS, San Diego, Aug 28-Sept 1, 2012.
- N. S. Lawand, P. J. French, J. J. Briaire, J. H. M. Frijns: “Thin TiN films deposited using DC magnetron sputtering for neural stimulation purposes”, Euroensors XXVI, Krakow, Sept. 9-12, 2012.

Results (width change) Potential at 30 μm from surface

Line Graph: Electric potential (V)

